

Title (en)
INTERCONNECTION STRUCTURE WITH LOW DIELECTRIC CONSTANT

Title (de)
VERBINDUNGSSTRUKTUR MIT NIEDRIGER DIELEKTRIZITÄTSKONSTANTE

Title (fr)
STRUCTURE D'INTERCONNEXION A FAIBLE CONSTANCE DIELECTRIQUE

Publication
EP 1665370 A1 20060607 (FR)

Application
EP 04816197 A 20040915

Priority
• FR 2004050435 W 20040915
• FR 0350547 A 20030916

Abstract (en)
[origin: FR2859822A1] The method involves fabricating an interconnection structure having an insulating layer (103) at the base of a dielectric material having dielectric constant, and a metallic connecting unit (110) in the layer. All or part of the dielectric material is partially removed. The material is replaced with another dielectric material (113) having dielectric constant less than or equal to the dielectric constant of the former material. An independent claim is also included for a micro-electromechanical system comprising an interconnection structure.

IPC 1-7
H01L 21/768

IPC 8 full level
H01L 21/768 (2006.01)

CPC (source: EP US)
H01L 21/76831 (2013.01 - EP US); **H01L 21/7688** (2013.01 - EP US); **H01L 21/76885** (2013.01 - EP US); **H01L 21/76834** (2013.01 - EP US)

Citation (search report)
See references of WO 2005029577A1

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